Am27C512L

65,536 x 8-Bit Ultra-Low CMOS EPROM

Advanced Devices

DISTINCTIVE CHARACTERISTICS

- Fast access time-70ns
- Ultra-low power consumption:
 - 5 mA maximum active current at 5 MHz
 - 20 μA maximum standby current
- Programming voltage: 12.75 V
- Single +5 -V power supply

- JEDEC-approved pinout
 - Plug in replacement for Am27C512
- ±10% power supply tolerance
- Fast Flashrite™ programming
 - Typical programming time of 15 seconds
- Latch-up protected to 100 mA from -1 V to Vcc +1 V

GENERAL DESCRIPTION

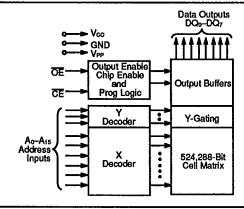
The Am27C512L is a 512K-bit, ultraviolet erasable programmable read-only memory. It is organized as 65,536 words by 8 bits per word, operates from a single +5-V supply, has a static standby mode, and features fast single address location programming. Products are available in windowed ceramic DIP and LCC packages, as well as plastic one-time programmable (OTP) packages.

Typically, any byte can be accessed in less than 70 ns. allowing operation with high-performance microprocessors without any WAIT states. The Am27C512L offers separate Output Enable (OE) and Chip Enable (CE) controls, thus eliminating bus contention in a multiple bus microprocessor system.

AMD's CMOS process technology provides high speed, low power, and high noise immunity. Typical power consumption is only 25 mW in active mode and 5 MHz operation, and 100 µW in standby mode and CMOS levels.

All signals are TTL levels, including programming signals. Bit locations may be programmed singly, in blocks, or at random.

BLOCK DIAGRAM



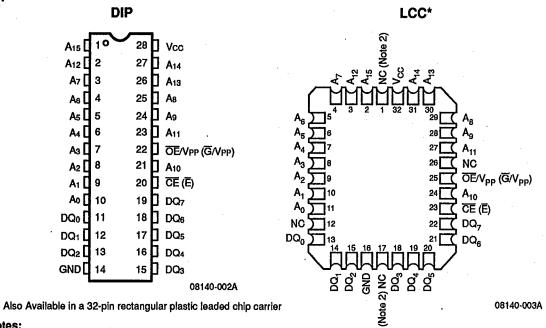
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PRODUCT SELECTOR GUIDE

Family Part No.				Am27C	512L	
Ordering Part Number ±5% Vcc Tolerance	-75	-95	-125			-255
±10% Vcc Tolerance	_	-90	-120	-150	-200	-250
Max. Access Time (ns)	70	90	120	150	200	250
CE (E) Access (ns)	70	90	120	150	200	250
OE (G) Access (ns)	40	40	50	50	75	100

CONNECTION DIAGRAMS Top View

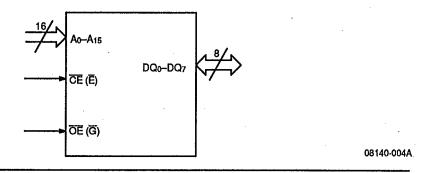
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Notes:

- JEDEC nomenclature is in parantheses.
 Don't use (DU) for PLCC.

LOGIC SYMBOL



PIN DESCRIPTION

Ao - A15 = Address inputs

CE (E) Chip Enable Input

DQ₀ – DQ₇ Data Inputs/Outputs

OE (G)

Output Enable Input

Vcc Vcc Supply Voltage

VPP **Program Supply Voltage**

GND Ground

NC No Internal Connection

DU No External Connection

ORDERING INFORMATION **Standard Products**

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0257528 0030385 4 **M**AMD4

ADV MICRO (MEMORY)

AMD standard products are available in several packages and operating ranges. The order number (Valid Combination) is formed by a combination of:

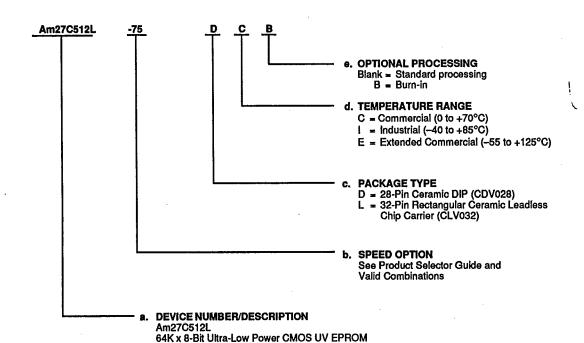
a. Device Number

b. Speed Option

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Package Type

C. Temperature Range Optional Processing



Valid Com	binations
Am27C512L-75	DC, DCB, LC, LCB
Am27C512L-95	DO DOD DI DID
Am27C512L-125	DC, DCB, DI, DIB, LC, LCB, LI, LIB
Am27C512L-90	20, 202, 21, 212
Am27C512L-120	DC, DCB, DI,
Am27C512L-150	DIB, DE, DEB,
Am27C512L-200	LC, LCB, LI, LIB, LE, LEB
Am27C512L-255	

Valid Combinations

Valid Combinations list configurations planned to be supported in volume for this device. Consult the lo-cal AMD sales office to confirm availability of specific valid combinations or to check on newly released combinations.

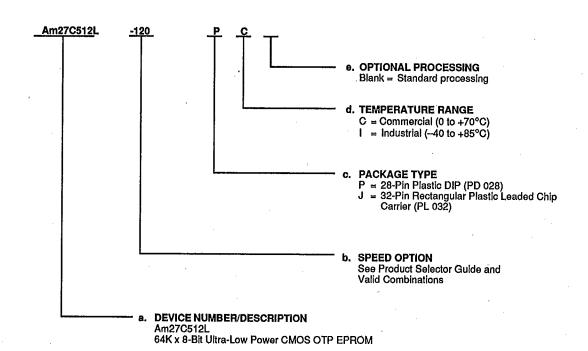
ORDERING INFORMATION **OTP Products**

ADV MICRO (MEMORY)

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AMD standard products are available in several packages and operating ranges. The order number (Valid Combination) is formed by a combination of:

a. Device Number
b. Speed Option
c. Package Type
d. Temperature Range
e. Optional Processing



Valid Comb	inations
Am27C512L-120	
Am27C512L-150	JC, PC,
Am27C512L-200	JI, PI
Am27C512L-255	

Valid Combinations

Valid Combinations list configurations planned to be supported in volume for this device. Consult the lo-cal AMD sales office to confirm availability of specific valid combinations or to check on newly released combinations.

MILITARY ORDERING INFORMATION APL Products

ADV MICRO (MEMORY)

AMD products for Aerospace and Defense applications are available in several packages and operating ranges. APL (Approved Products List) products are fully compliant with MIL-STD-883C requirements. The order number (Valid Combination) is formed by a combination of:

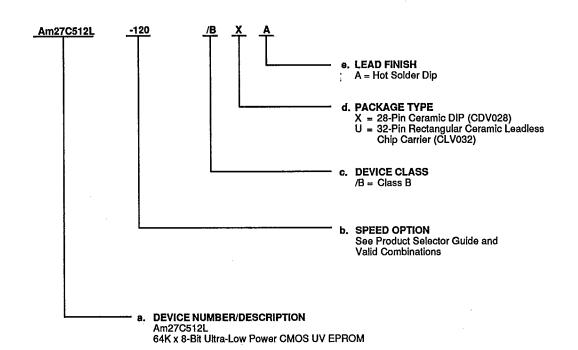
a. Device Number

b. Speed Option

c. Package Type
d. Temperature Range
e. Lead Finish

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Valid Com	binations
Am27C512L-120	
Am27C512L-150	/BXA, /BUA
Am27C512L-200	/BAA, /BUA
Am27C512L-250	

Valid Combinations

Valid Combinations list configurations planned to be supported in volume for this device. Consult the local AMD sales office to confirm availability of specific valid combinations, or to check on newly released combinations.

Group A Tests

Group A tests consist of Subgroups 1, 2, 3, 7, 8, 9, 10, 11.

FUNCTIONAL DESCRIPTION Erasing the Am27C512L

In order to clear all locations of their programmed contents, it is necessary to expose the Am27C512L to an ultraviolet light source. A dosage of 15 W seconds/cm² is required to completely erase an Am27C512L. This dosage can be obtained by exposure to an ultraviolet lamp—wavelength of 2537 Angstroms (Å)—with intensity of 12,000 $\mu\text{W/cm}^2$ for 15 to 20 minutes. The Am27C512L should be directly under and about one inch from the source and all filters should be removed from the UV light source prior to erasure.

It is important to note that the Am27C512L, and similar devices, will erase with Jight sources having wavelengths shorter than 4000 Å. Although erasure times will be much longer than with UV sources at 2537 Å, nevertheless the exposure to fluorescent light and sunlight will eventually erase the Am27C512L and exposure to them should be prevented to realize maximum system reliability. If used in such an environment, the package window should be covered by an opaque label or substance

Programming the Am27C512L

Upon delivery, or after each erasure, the Am27C512L has all 524,288 bits in the "ONE", or HIGH state. "ZE-ROs" are loaded into the Am27C512L through the procedure of programming.

The programming mode is entered when 12.75 \pm 0.25 V is applied to the OE/V_{PP} pin, and CE is at V_H.

For programming, the data to be programmed is applied 8 bits in parallel to the data output pins.

The Flashrite programming algorithm (shown in Figure 1) reduces programming time by using initial 100 μs pulses followed by a byte verification to determine whether the byte has been successfully programmed. If the data does not verify, an additional pulse is applied for a maximum of 25 pulses. This process is repeated while sequencing through each address of the EPROM.

The Flashrite programming algorithm programs and verifies at $Vcc = 6.25 \, V$ and $Vpp = 12.75 \, V$. After the final address is completed, all bytes are compared to the original data with $Vcc = Vpp = 5.25 \, V$.

Program Inhibit

Programming of multiple Am27C512Ls in parallel with different data is also easily accomplished. Except for \overline{CE} , all like inputs of the parallel Am27C512L including \overline{OE}/V_{PP} may be common. A \overline{TTL} low-level program pulse applied to an Am27C512L \overline{CE} input with \overline{OE}/V_{PP} = 12.75 \pm 0.25 V will program that Am27C512L. A high-level \overline{CE} input inhibits the other Am27C512Ls from being programmed.

ADV MICRO (MEMORY)

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Program Verify

A verify should be performed on the programmed bits to determine that they were correctly programmed. The verify should be performed with $\overrightarrow{OE}/V_{PP}$ and \overrightarrow{CE} at V_{IL} . Data should be verified tov after the falling edge of \overrightarrow{CE} .

Auto Select Mode

The auto select mode allows the reading out of a binary code from an EPROM that will identify its manufacturer and type. This mode is intended for use by programming equipment for the purpose of automatically matching the device to be programmeed with its corresponding programming algorithm. This mode is functional in the $25^{\circ}\text{C} \pm 5^{\circ}\text{C}$ ambient temperature range that is required when programming the Am27C512L.

To activate this mode, the programming equipment must force 12.0 \pm 0.5 V on address line A₉ of the Am27C512L... Two identifier bytes may then be sequenced from the device outputs by toggling address line A₀ from V_{IL} to V_{IH}. All other address lines must be held at V_{IL} during auto select mode.

Byte 0 ($A_0 = V_{IL}$) represents the manufacturer code, and byte 1 ($A_0 = V_{IH}$), the device identifier code. For the Am27C512L, these two identifier bytes are given in the Mode Select table. All identifiers for manufacturer and device codes will possess odd parity, with the MSB (DQ₇) defined as the parity bit.

Read Mode

The Am27C512L has two control functions, both of which must be logically satisfied in order to obtain data at the outputs. Chip Enable (\overline{CE}) is the power control and should be used for device selection. Output Enable (\overline{OE}) is the output control and should be used to gate data to the output pins, independent of device selection. Assuming that addresses are stable, address access time (tacc) is equal to the delay from \overline{CE} to output (tcE). Data is available at the outputs tOE after the falling edge of \overline{OE} , assuming that \overline{CE} has been LOW and addresses have been stable for at least tacc—toE.

Standby Mode

The Am27C512L has a CMOS standby mode which reduces the maximum Vcc current to 20 μ A. It is placed in CMOS-standby when \overline{CE} is at Vcc \pm 0.3 V. The Am27C512L also has a TTL-standby mode which reduces the maximum Vcc current to 1.0 mA. It is placed in TTL-standby when \overline{CE} is at V μ H. When in standby mode, the outputs are in a high-impedance state, independent of the \overline{OE} input.

Output OR-Tieing

To accomodate multiple memory connections, a twoline control function is provided to allow for:

- 1. Low memory power dissipation, and
- 2. Assurance that output bus contention will not occur.

It is recommended that \overline{CE} be decoded and used as the primary device-selecting function, while \overline{OE} be made a common connection to all devices in the array and connected to the READ line from the system control bus. This assures that all deselected memory devices are in their low-power standby mode and that the output pins are only active when data is desired from a particular memory device.

System Applications

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During the switch between active and standby conditions, transient current peaks are produced on the rising and falling edges of Chip Enable. The magnitude of these transient current peaks is dependent on the output capacitance loading of the device. At a minimum, a 0.1 μF ceramic capacitor (high frequency, low inherent inductance) should be used on each device between Vcc and GND to minimize transient effects. In addition, to overcome the voltage drop caused by the inductive effects of the printed circuit board traces on EPROM arrays, a 4.7 μF bulk electrolytic capacitor should be used between Vcc and GND for each eight devices. The location of the capacitor should be close to where the power supply is connected to the array.

Mode Select Table

Mode	Pins	CE	OE/V _{PP}	Ao	A9	Outputs
Read		VIL	ViL	Х	Х	Dour
Output D	isable	VıL	ViH	Х	X	High Z
Standby	(TTL)	ViH	Х	Х	Х	High Z
Standby	(CMOS)	Vcc ± 0.3 V	х	Х	х	High Z
Program		Vil	Vpp	Х	Х	DiN
Program	Verify	VIL	ViL	Х	Х	Douт
Program	Inhibit	ViH	Vpp	Х	Х	High Z
Auto Select	Manufacturer Code	Vil	V⊩	VIL	Vн	01H
(Note 3)	Device Code	VIL	VIL	ViH	VH	91H

- 1. X can be either VIL or VIH
- 2. VH = 12.0 V ± 0.5 V
- 3. A1-A8 = A10-A15 = ViL
- 4. See DC Programming Characteristics for VPP voltage during programming.

ADV MICRO (MEMORY) PRELIMINARY

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ABSOLUTE MAXIMUM RATINGS

Storage Temperature:

OTP Products -65 to + 125°C All Other Products -65 to + 150°C

Ambient Temperature with Power Applied

-55 to +125°C

Voltage with Respect to Ground: All pins except As, VPP, and

Vcc (Note 1)

-0.6 to Vcc + 0.6 V

As and Vpp (Note 2) Vcc

-0.6 to 13.5 V -0.6 to 7.0 V

Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only; functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure of the device to absolute maximum rating conditions for extended periods may affect device reliability.

Notes:

- During transitions the inputs may undershoot GND to -2.0 V for periods of up to 20 ns. Maximum DC voltage on input and I/O may overshoot to Vcc + 2.0 V for periods up to 20 ns.
- 2. During transitions, A9 and Vpp may undershoot GND to -2.0 V for periods of up to 20 ns. As and VPP must not exceed 13.5 V for any period of time.

T-46-13-29 **OPERATING RANGES**

Commercial (C) Devices

Case Temperature (Tc) 0 to +70°C

Industrial (I) Devices

Case Temperature (Tc) -40 to +85°C

Extended Commercial (E) Devices

Case Temperature (Tc) -55 to +125°C

Military (M) Devices

Case Temperature (Tc) -55 to +125°C

Supply Read Voltages:

Vcc/VPP for Am27C512L-XX5 +4.75 to +5.25 V

Vcc/VPP for Am27C512L-XX0 +4.50 to +5.50 V

Operating ranges define those limits between which the functionality of the device is guaranteed.

DC CHARACTERISTICS over operating range unless otherwise specified (Notes 1, 4, 5 & 7)

TTL and NMOS

Parameter Symbol	Parameter Description	Test Conditions	•	Min.	Max.	Unit
Vон	Output HIGH Voltage	Іон = -400 μΑ		2.4		٧
Vol	Output LOW Voltage	loL = 2.1 mA			0.45	٧
ViH	Input HIGH Voltage			2.0	Vcc + 0.5	V
ViL	Input LOW Voltage			-0.3	+0.8	٧
lu	Input Load Current	Vin = 0 V to Vcc	C/I Devices E/M Devices		1.0 5.0	μΑ
lro	Output Leakage Current	Vout = 0 V to Vcc	C/I Devices E/M Devices		2.0 5.0	μА
Icc ₁	Vcc Active Current (Note 5)	CE = VIL, f = 10 MHz,	C/I Devices		15	mA
	•	lout = 0 mA (Open Outputs)	E/M Devices		25	
lcc2	Vcc Standby Current	CE = ViH,	C/I Devices		1.0	mA
		OE = VIL	E/M Devices		1.0	

DC CHARACTERISTICS over operating range unless otherwise specified (Continued)

CMOS					_′ T–46∙	-13-29
Parameter Symbol	Parameter Description	Test Conditions		Min.	Max.	Unit
Vон	Output HIGH Voltage	Ioн = -400 μA		Vcc - 0.8		٧
Vol	Output LOW Voltage	loL = 2.1 mA			0.45	٧
ViH .	Input HIGH Voltage			0.7 Vcc	Vcc + 0.5	V
VIL	Input LOW Voltage	_		-0.5	+0.8	٧
1Lt	Input Load Current	Vin = 0 V to Vcc	C/I Devices E/M Devices		1.0	μА
lLO	Output Leakage Current	Vout = 0 V to Vcc	C/I Devices E/M Devices		2.0 5.0	μΑ
lcc ₁	Vcc Active Current (Note 5 & 8)	CE = VIL, f = 5 MHz,	C/I Devices		5.0	mA
	,	lout = 0 mA (Open Outputs)	E/M Devices		10	
lcc2	Vcc Standby Current	CE = Vcc ± 0.3 V	C/I Devices		20	μΑ
	1	1	E/M Devices		40	

CAPACITANCE (Notes 2, 3, & 6)

Parameter Symbol	Parameter Description	Test Conditions	CDV028 Max.	CLV032 Max.	Unit
Cint	Address Input Capacitance	VIN = 0 V	12	9	pF
CIN2	OE/VPP Input Capacitance	VIN = 0 V	20	20	pF
Cina	CE Input Capacitance	VIN = 0 V	12	9	pF
Соит	Output Capacitance	Vout = 0 V	15	12	pF

- 1. Vcc must be applied simultaneously or before Vpp, and removed simultaneously or after Vpp.
- 2. Typical values are for nominal supply voltages.
- 3. This parameter is only sampled and not 100% tested.
- 4. Caution: The Am27C512L must not be removed from, or inserted into, a socket or board when Vpp or Vcc is applied.
- 5. Icc1 is tested with $\overline{OE} = V_{IH}$ to simulate open outputs.
- 6. $TA = 25^{\circ}C$, f = 1 MHz.
- During transitions, the inputs may overshoot to -2.0 V for periods less than 20 ns. Maximum DC voltage on input pins may overshoot to Vcc + 2.0 V for periods less than 20 ns.
- 8. Icc1 varies 1 mA per MHz for C/I devices. Icc1 varies 2 mA per MHz for E/M devices.

SWITCHING CHARACTERISTICS over operating ranges unless otherwise specified (Notes 1, 3, & 4) T-46-13-29

meter						A	m27C	512L		
bols Standard	Parameter Description	Test Conditi	ons	-75	-90, -95	-120, -125	-150	-200	-255, -250	Unit
tacc	Address to Output Delay	CE = OE/Vpp = VIL	Min. Max.	70	90	120	150	200	250	ns
tce	Chip Enable to Output Delay	OE/Vpp = VIL	Min. Max.	70	90	120	150	200	250	ns
toe	Output Enable to Output Delay	CE = V _{IL}	Min. Max.	40	40	50	50	75	100	ns
to⊧	Output Enable HIGH to Output Float (Note 2)		Min. Max.	25	30	30	30	30	30	ns
tон	Output Hold from Addresses, CE, or OE, whichever		Min.	0	0	0	0	0	0	ns
	tacc toe toe	bols Parameter Standard Description tACC Address to Output Delay tCE Chip Enable to Output Delay toe Output Enable to Output Delay top Output Enable HIGH to Output Float (Note 2) toh Output Hold from Addresses, CE, or OE,	Description Test Condition	Standard Description Test Conditions	Test Conditions Test Condi	Standard Description Test Conditions -75 -95 -95 tacc	Description Test Conditions Foundation Test Conditions Foundation Test Conditions Foundation Foundation Test Conditions Foundation Foundat	Test Conditions	Standard Description Test Conditions -75 -90, -120, -120 -200	Name

Notes:

- 1. Vcc must be applied simultaneously or before Vpp, and removed simultaneously or after Vpp.
- 2. This parameter is only sampled and not 100% tested.
- 3. Caution: The Am27C512L must not be removed from, or inserted into, a socket or board when VPP or Vcc is applied.
- 4. For the Am27C512L-75;

Output Load: 1 TTL gate and CL = 30 pF,

Input Rise and Fall Times: 20 ns,

Input Pulse Levels: 0 to 3 V,

Timing Measurement Reference Level: 1.5 V for inputs and outputs.

For all other versions:

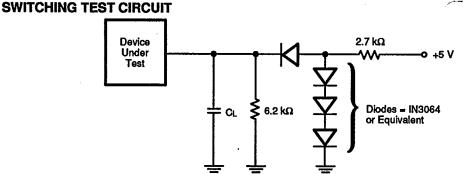
Output Load: 1 TTL gate and CL = 100 pF,

Input Rise and Fall Times: 20 ns, Input Pulse Levels: 0.45 to 2.4 V,

Timing Measurement Reference Level: 0.8 V and 2 V for inputs and outputs.

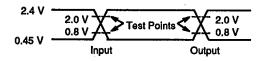


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CL = 100 pF including jig capacitance (30 pF for -75)

SWITCHING TEST WAVEFORMS



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AC Testing: Inputs are driven at 2.4 V for a logic "1" and 0.45 V for a logic "0". Input pulse rise and fall times are ≤ 20 ns.

AC Testing: Inputs are driven at 3.0 V for a logic "1" and 0 V for a logic "0". Input pulse rise and fall times are ≤ 20 ns for -75 devices.

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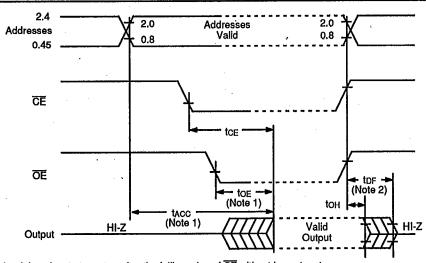
SWITCHING WAVEFORMS

Key to Switching Waveforms

WAVEFORM	INPUTS	OUTPUTS
	Must be Steady	Will be Steady
	May Change from H to L	Will be Changing from H to L
	May Change from L to H	Will be Changing from L to H
	Don't Care, Any Change Permitted	Changing, State Unknown
>>	Does Not Apply	Center Line is High- Impedance "Off" State

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- OE may be delayed up to tacc-toe after the falling edge of CE without impact on tacc.
 toe is specified from OE or CE, whichever occurs first.

Figure 1. Flashrite Programming Flow Chart

Verify All Bytes ?

Device Passed

Pass

Fail

Device Failed

06780-008E

DC PROGRAMMING	CHARACTERISTICS ($T_A = +25^{\circ}C \pm 5^{\circ}C)$) (Notes 1, 2, & 3) 🥤

Parameter Symbol	Parameter Description	Test Conditions	Min.	Max.	Unit
lu	Input Current (All Inputs)	VIN = VIL OF VIH		10.0	μΑ
VIL	Input LOW Level (All Inputs)		-0.3	0.8	٧
ViH	Input HIGH Level		2.0	Vcc + 0.5	. V
Vol	Output LOW Voltage During Verify	loj. = 2.1 mA		0.45	٧
Vон	Output HIGH Voltage During Verify	loн = −400 μA	2.4		٧
Vн	A ₉ Auto Select Voltage		11.5	12.5	٧
lcc	Vcc Supply Current (Program & Verify)			50	mA
lpp	V _{PP} Supply Current (Program)	CE = VIL		30	mA
Vcc	Flashrite Supply Voltage		6.00	6.50	V
Vpp	Flashrite Programming Voltage		12.5	13.0	V

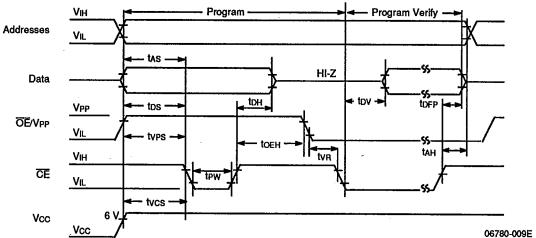
SWITCHING PROGRAMMING CHARACTERISTICS ($T_A = +25$ °C ± 5 °C) (Notes 1, 2, & 3)

Parameter Symbols		Parameter		ŀ	
JEDEC	Standard	Description	Min.	Max.	Unit
tavel	tas	Address Setup Time	2		μs
t DVEL	tos	Data Setup Time	2	-	μs
tghax	tah	Address Hold Time	0		μs
TEHDX	ton	Data Hold Time	2		μs
t EHQZ	tofp	Chip Enable to Output Float Delay	0	60	ns
tves	tvps	V _{PP} Setup Time	2		μs
teleh	tpw	CE Program Pulse Width	95	105	μs
tvcs	tvcs	Vcc Setup Time	2		μs
telav	tov	Data Valid from CE		250	ns
tehgl.	t oeh	OE/V _{PP} Hold Time	2		μs
t GLEL	tvn	OE/V _{PP} Recovery Time	2		μs

- 1. Vcc must be applied simultaneously or before Vpp, and removed simultaneously or after Vpp.
- 2. When programming the Am27C512L, a 0.1 μF capacitor is required across Vpp and ground to suppress spurious voltage transients which may damage the device.
- 3. Programming characteristics are sampled but not 100% tested at worst-case conditions.

PROGRAMMING ALGORITHM WAVEFORMS (Notes 1 & 2)

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- 1. The input timing reference level is 0.8 V for VIL and 2.0 V for VIH.
- 2. top and topp are characteristics of the device, but must be accommodated by the programmer.